

Features

- Metal foil chip design for overcurrent protection
- EIA 0603 (1608 metric) footprint
- Small chip size with high current rating and inrush withstanding capability
- Agency recognition: c **Tu**us





- RoHS* compliant and halogen free**
- AEC-Q200 Rev. E compliant

SF-0603SPA-R Series – Automotive Grade SMD Fuses

Clearing Time Characteristics for Series

9/ of Current Boting	Clearing Ti	me at 25 °C
% of Current Rating	Min.	Max.
100 %	4 hours	_
200 %	1 second	120 seconds

Additional Information

Click these links for more information:











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INVENTORY SAMPLES

Electrical Characteristics

	Rated	Resistance	Rated	Interrupting	Rated Interrupting	Typical	Certific	cations	
Model	Current (A)	(Ω) Typ. ¹	Voltage ¹	Rating ²	I ² t (A ² s) ³	cUL: <u>E198545</u>	TÜV: <u>TA50515766</u>		
SF-0603SPA100R-2	1.0	0.115	50 VDC 63 VDC				0.059	✓	1
SF-0603SPA150R-2	1.5	0.059				0.13	✓	1	
SF-0603SPA200R-2	2.0	0.033			50 VDC 63 VDC		0.21	✓	✓
SF-0603SPA300R-2	3.0	0.0159					0.71	✓	1
SF-0603SPA400R-2	4.0	0.01				50 A @ 50 VDC 50 A @ 63 VDC	0.96	1	1
SF-0603SPA500R-2	5.0	0.00677				0071 00 120	2.05	✓	1
SF-0603SPA600R-2	6.0	0.0063				3.47	✓	1	
SF-0603SPA700R-2	7.0	0.0047				5.04	/	✓	
SF-0603SPA800R-2	8.0	0.0043			6.5	1	1		

Notes:

- 1. Resistance value measured with ≤10 % rated current at 25 °C ambient. Tolerance ±25 %.
- 2. UL: 50 A @ 63 VDC / TUV: 50 A @ 50 VDC
- 3. Melting I²t calculated at 0.001 second pre-arcing time.

BOURNS®

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CALIFORNIA WARNING Can expose you to lead, a carcinogen and reproductive toxicant. See www.P65Warnings.ca.gov

*RoHS Directive 2015/863, Mar 31, 2015 and Annex.

"SinglFuse" is a trademark of Bourns, Inc.

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

The products described herein and this document are subject to specific legal disclaimers as set forth on the last page of this document, and at www.bourns.com/docs/legal/disclaimer.pdf.

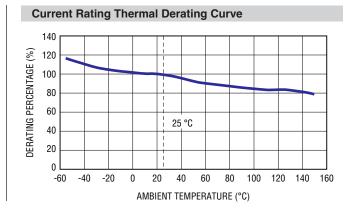
^{**}Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less; (b) the Chlorine (CI) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (CI) content is 1500 ppm or less.

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Environmental Characteristics

Operating Temperature	-55 °C to +150 °C
Storage Conditions	
Temperature	+5 °C to +35 °C
Humidity	40 % to 75 %
Moisture Sensitivity Level	1
ESD Classification ¹	Class 6

¹per AEC-Q200-2, HBM



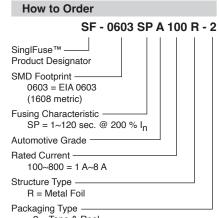
Typical Part Marking

Represents total content. Layout may vary. Markings in white color.



Rated Current	Part Marking
1 A	L
1.5 A	Р
2 A	S
3 A	3
4 A	W

Rated Current	Part Marking
5 A	Υ
6 A	<u>6</u>
7 A	7
8 A	8

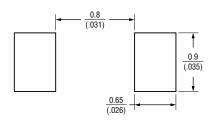


- 2 = Tape & Reel

Packaging

Reel Dimension	7-inch Tape and Reel
Specification	EIA 481-2
Quantity	5,000 pieces
Packaging Code	-2

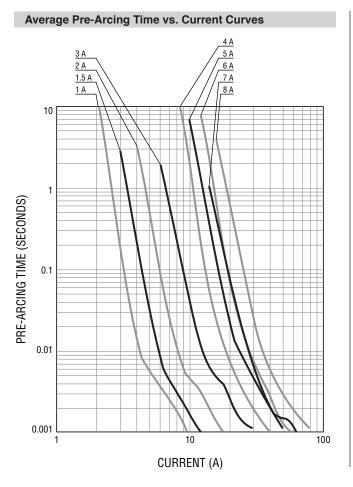
Recommended Pad Layout

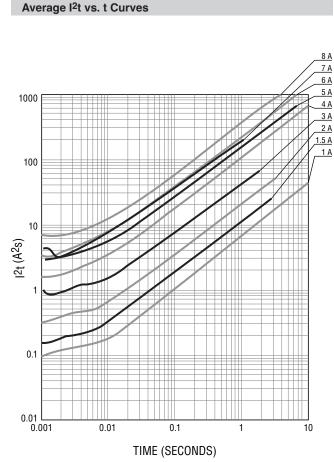


MM DIMENSIONS: (INCHES)

Product Dimensions	
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DIMENSIONS:	MM (INCHES)

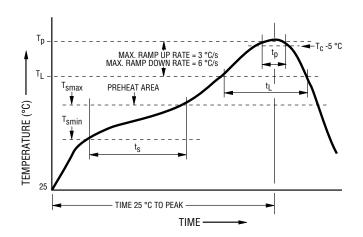
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Solder Reflow Recommendations



Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	150 °C 200 °C 60~120 seconds
Ramp Up Rate (T _L to T _p)	3 °C / second max.
Liquidous Temperature (T _L) Time (t _L) maintained above T _L	217 °C 60~150 seconds
Peak Package Body Temperature (T _p)	260 °C
Time (t _p)* within 5 °C of the specified classification temperature (T _c)	30 seconds*
Ramp Down Rate (T _p to T _L)	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

Reliability Tests

Test Items	Reference Standard
Solderability	J-STD-002; Condition B
Resistance to Soldering Heat	MIL-STD-202; Method 210; Condition B
Moisture Resistance	MIL-STD-202; Method 106
Thermal Shock	MIL-STD-202; Method 107; Condition B
Mechanical Shock	MIL-STD-202; Method 213; Condition A
Vibration	MIL-STD-202; Method 201
Terminal Strength	IEC 60115-1 4.32
High Temperature Storage	MIL-STD-202; Method 108
Temperature Cycling	JESD22 Method JA-104, Test Conditions B and N
Bias Humidity	MIL-STD-202; Method 103
Operational Life	MIL-STD-202; Method 108; Condition D
Resistance to Solvent	MIL-STD-202; Method 215
Board Flex (Bending)	AEC-Q200-005
Carrying Capacity	UL 248-14
Fusing Time	UL 248-14
Interrupting Ability	UL 248-14
Temperature Rise	UL 248-14
Residual Resistance	UL 248-14
Low Temperature Storage	JESD22-A119